



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

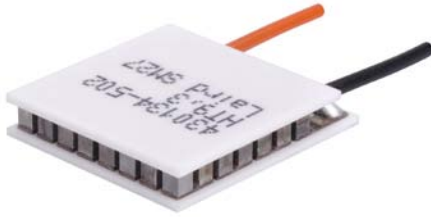
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



ThermaTEC™ Series HT9-3-F2-2525

Thermoelectric Modules



The ThermaTEC™ Series of thermoelectric modules (TEMs) are designed to operate under cycling conditions or high temperature applications.

This product line is available in multiple configurations and is ideal for applications that require both heating and cooling mode (reverse polarity) or power generation. Assembled with proprietary solder construction, Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the ThermaTEC Series is designed for higher current and larger heat-pumping applications.

Americas: +1.919.597.7300
Europe: +46.31.420530
Asia: +86.755.2714.1166
ets.sales@lairdtech.com
www.lairdtech.com

FEATURES

- Thermal cycling durability
- Power cycling reliability
- Precise temperature control
- Strong lead attachment
- RoHS compliant
- Continuous operation at high temperatures

APPLICATIONS

- Analytical instrumentation
- PCR cyclers
- Thermal test sockets
- Electronic enclosure cooling
- Chillers (liquid cooling)
- Power generation

SPECIFICATIONS

TECHNICAL		
Hot Side Temperature (°C)	25°C	50°C
Qmax (Watts)	20.1	22.1
Delta Tmax (°C)	63	75
I _{max} (Amps)	9.6	9.6
V _{max} (Volts)	3.6	4.0
Module Resistance (Ohms)	0.34	0.38

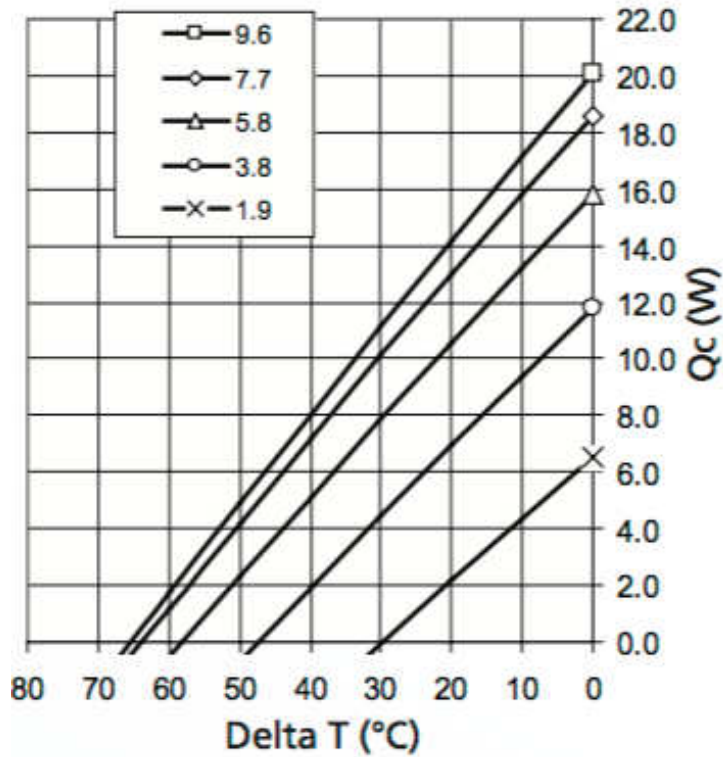
SUFFIX	THICKNESS (PRIOR TO TINNING)	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
11	0.197"±0.005"	0.002" /0.0035"	Lapped	Lapped	6.0"
TA	0.197"±0.001"	0.001"/0.001"	Lapped	Lapped	6.0"
TB	0.197"±0.0005"	0.0005"/0.0005"	Lapped	Lapped	6.0"

SEALING OPTIONS

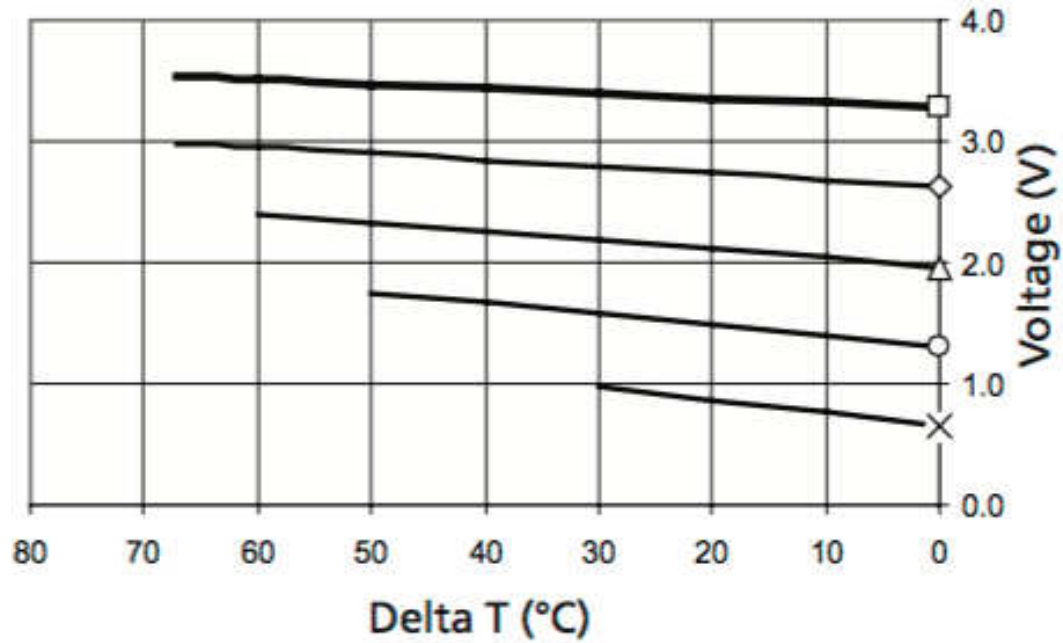
SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
RT	RTV	White	-60 to 204 °C	Non-corrosive, silicone adhesive
EP	Epoxy	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

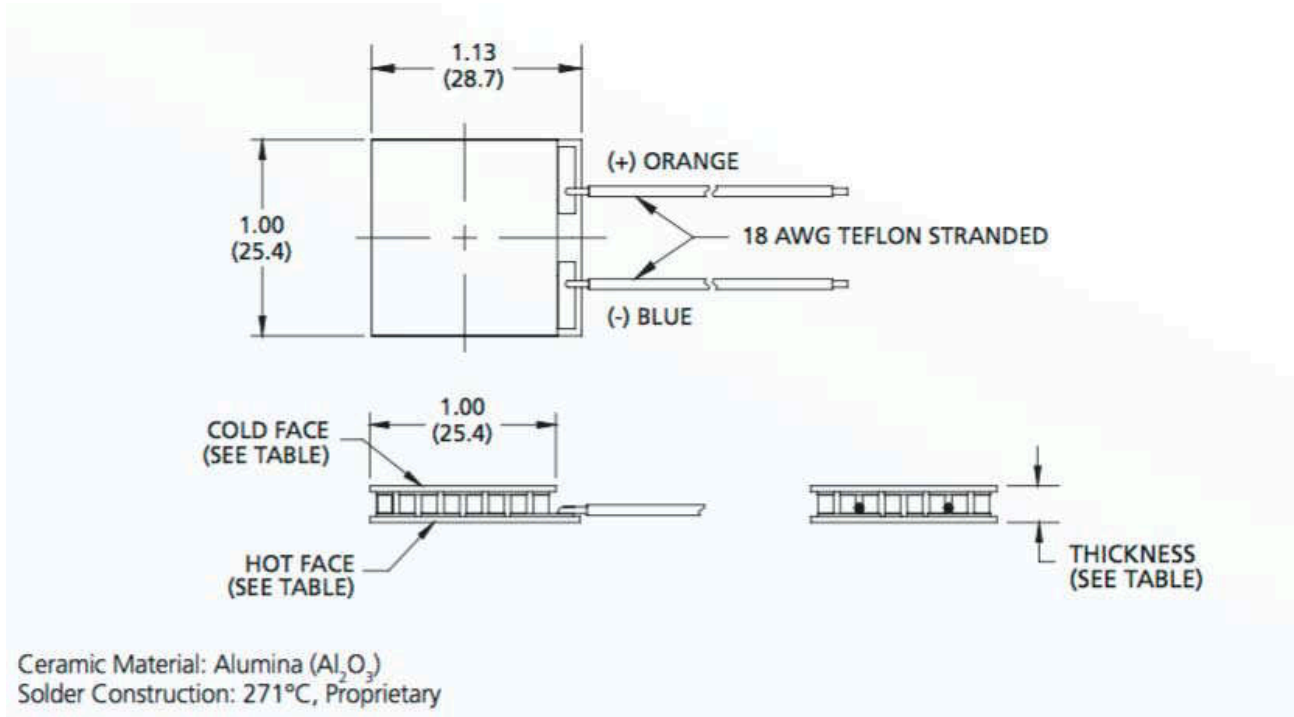
Performance Curves at Th = 25°C

THERMO



ELECTRIC





NOTES

1. Max operating temperature: 175°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation

LAIRD-ETS-HT9-3-F2-2525-DATA-SHEET-101416

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